



10 - 12 - 06

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re: Appn. Ser. No. 10/733,672

Art Unit 2835

Filed 12/11/03 : M.V. Datskovsky

Inventors L.S. Mok et al. : Atty Dkt No. YOR920030186US1

For: CHIP PACKAGING MODULE WITH ACTIVE COOLING MECHANISMS

EXPRESS MAIL CERTIFICATE

Commissioner for Patents  
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Receipt of the 9/18/06 Office Communication, containing an assertion of abandonment resulting from a reply to a 12/21/05 Office Communication, assumed as not being received, is acknowledged herewith. However, the assertion is refuted by the attached receipt stamp indicating that a response was received 1/20/06.

The response included the response, an Information Disclosure Transmittal with reference copies and proposed replacement informal drawings transmitted under the Express Mail Label No. ED 882445249US.

Respectfully submitted,  
*Alvin J. Riddles 10/12/06*  
Alvin J. Riddles  
Reg. No. 17862

PLEASE STAMP AND RETURN

Appn. Ser No. 10/733,672 : Art Unit. 2835

Filed 12/11/03 : Exr. M.V. Datskovskiy

Inventor L.S. Mokerak : Atty/Art. YDR920030186 US1

RECEIVED IN THE U.S. PATENT AND TRADEMARK OFFICE  
RESPONSE TO 12/21/05 OFFICE COMMUNICATION





IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re. Appn. Ser. No. 10/733,672 : Art Unit 2835  
Filed 12/11/03 : Examiner M.V. Dotskoyskiy  
Inventors L.S.Mok et al. : Atty. Dkt. No. YOR920030186US1  
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